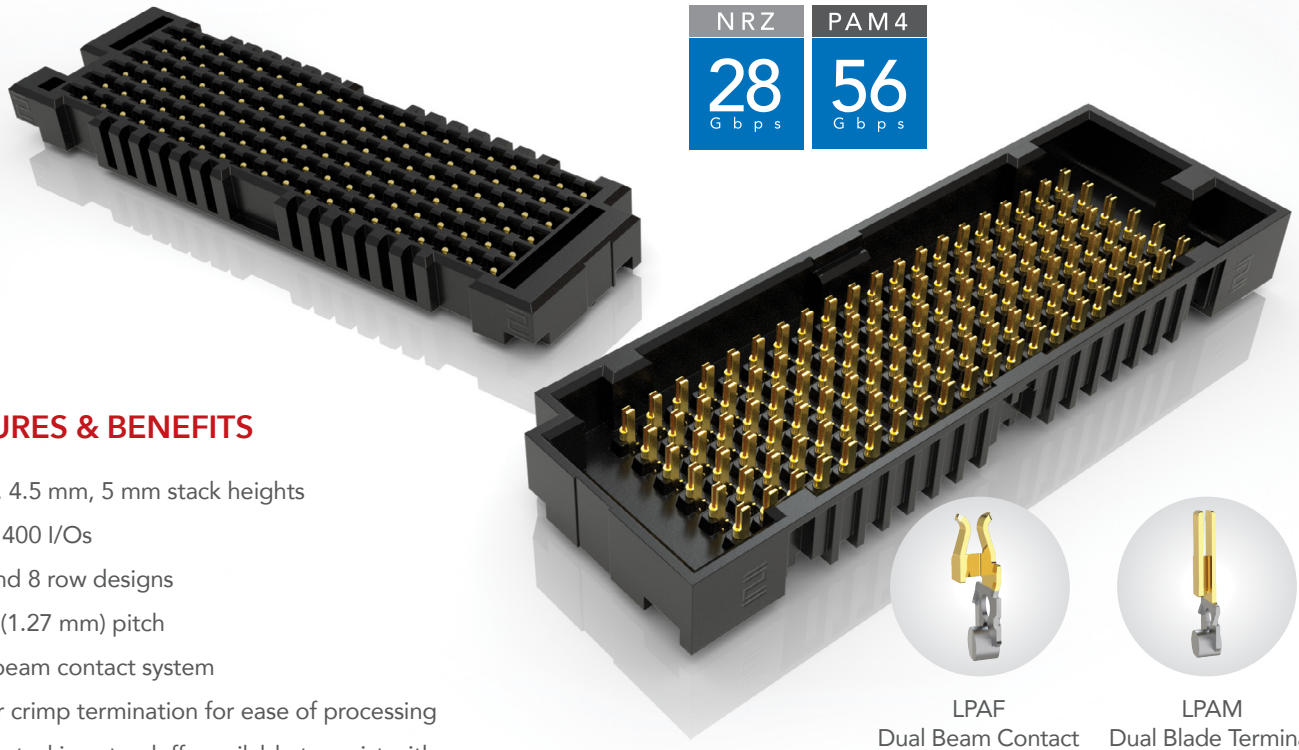
LP ARRAY™

LOW PROFILE OPEN-PIN-FIELD ARRAYS

(1.27 mm) .050" PITCH

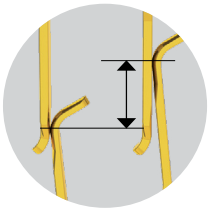


LPAF
Dual Beam Contact

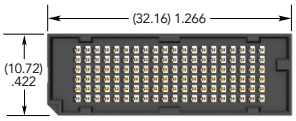
LPAM
Dual Blade Terminal

FEATURES & BENEFITS

- 4 mm, 4.5 mm, 5 mm stack heights
- Up to 400 I/Os
- 4, 6 and 8 row designs
- .050" (1.27 mm) pitch
- Dual beam contact system
- Solder crimp termination for ease of processing
- Board stacking standoffs available to assist with unmating and reduce risk for component damage on board

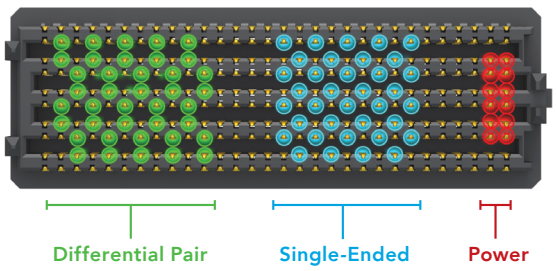


(0.51 mm) .020"
Nominal Wipe



LPAM Series; 120 pins

MAXIMUM GROUNDING & ROUTING FLEXIBILITY



KEY SPECIFICATIONS (LPAM/LPAF)

PITCH	TOTAL PINS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
1.27 mm x 1.27 mm	Up to 400 I/Os	Black LCP	Copper Alloy	Au or Sn over 50 µ" (1.27 µm) Ni	2.2 A per pin (8 adjacent pins powered)	250 VAC/354 VDC	YES

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.

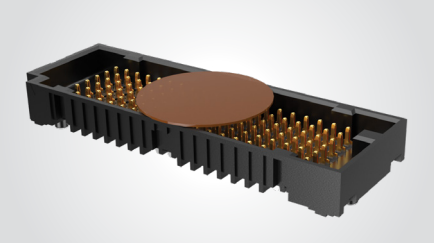
(1.27 mm) .050" PITCH • LOW PROFILE OPEN-PIN-FIELD ARRAYS

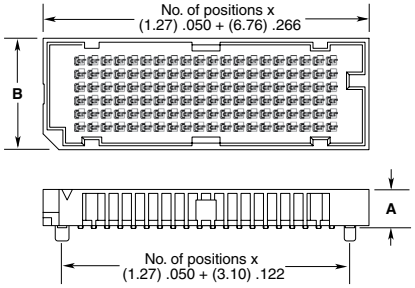
SERIES	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	K	"X"R
LPAM Terminal **LPAF** Socket	**–10, –20, –30, –40,** **–50** (-08 rows only)	**–01.0** = (1.0 mm) .039" (LPAM only) **–01.5** = (1.5 mm) .060" (LPAM only) **–03.0** = (3.0 mm) .118" (LPAF only) **–03.5** = (3.5 mm) .138" (LPAF only)	**–L** = 10 µ" (0.25 µm) Gold on contact area, Matte Tin on solder tail **–S** = 30 µ" (0.76 µm) Gold on contact area, Matt Tin on solder tail	**–04** **–06** **–08**	**–1** = Tin/Lead Alloy Solder Crimp **–2** = Lead-Free Solder Crimp	**–K** = Polyimide film Pick & Place Pad	**–TR** = Tape & Reel **–FR** = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

LPAM

Board Mates: LPAF

Standoffs: JSO, SO





NO. OF ROWS	B
–04	(8.18) .322
–06	(10.72) .422
–08	(13.26) .522

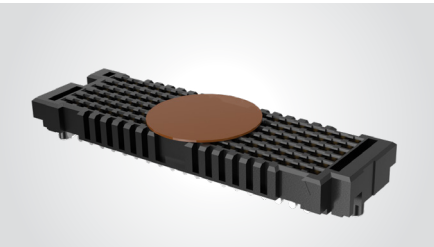
LEAD STYLE	A
-01.0	(3.68) .145
-01.5	(4.19) .165

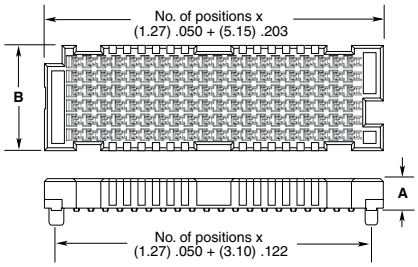
View complete specifications at: samtec.com?LPAM

LPAF

Board Mates: LPAM

Standoffs: JSO, SO





NO. OF ROWS	B
–04	(6.71) .264
–06	(9.25) .364
–08	(11.79) .464

LEAD STYLE	A
-03.0	(2.79) .110
-03.5	(3.30) .130

MATED HEIGHTS*

LPAM LEAD STYLE	LPAF LEAD STYLE	
	-03.0	-03.5
-01.0	(4.00) .157	(4.50) .177
-01.5	(4.50) .177	(5.00) .197

*Processing conditions will affect mated height.

Notes:
Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?LPAF

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